

General Description

The WSF4060 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications . The WSF4060 meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

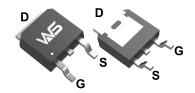
Product Summery

BVDSS	RDSON	ID
40V	7.2mΩ	60A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Power Tool Application

TO-252 Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	40	V	
V_{GS}	Gate-Source Voltage	±20	V	
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V	60	Α	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V	48	Α	
I _{DM}	Pulsed Drain Current ^a	160	А	
EAS	Single Pulse Avalanche Energy ^b	100	mJ	
I _{AS}	Avalanche Current 60		Α	
P _D @T _a =25℃	Total Power Dissipation	3.0	W	
T _{STG}	Storage Temperature Range	-55 to 150	$^{\circ}$	
T_J	Operating Junction Temperature Range -55 to 150		$^{\circ}$	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹		50	°C/W
R _{eJC}	Thermal Resistance Junction-Case ¹		2.5	°C/W

Notes:

- * Avalanche single pulse test and avalanche period time tav \leq 100 μ s, duty<1% .
- ** Avalanche test condition: T_J =25°C, L=0.5mH, I_{AS} =20A, V_{DD} =30V, and V_{GS} =10V.

^{***} Current limited by bond wire.



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0 V , I_D =250 u A	40			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25℃, I _D =1mA		0.043		V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =20A		7.2	9.0	mΩ
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =10A		9.2	13	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	-V _{GS} =V _{DS} , I _D =250uA	1.2	1.6	2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} -V _{DS} , I _D -250uA		-6.94		mV/℃
1	Drain-Source Leakage Current	V _{DS} =32V , V _{GS} =0V , T _J =25℃			2	
I _{DSS}		V _{DS} =32V , V _{GS} =0V , T _J =55°C			10	· uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =20A		33		S
R_g	Gate Resistance	V_{DS} =0V , V_{GS} =0V , f=1MHz		1.4	2	Ω
Q_g	Total Gate Charge (10V)	V _{DS} =20V , V _{GS} =10V , I _D =40A		32	44	
Q _{gs}	Gate-Source Charge			3.8		nC
Q_{gd}	Gate-Drain Charge			9.0		
T _{d(on)}	Turn-On Delay Time	V_{DD} =30V , V_{GEN} =10V , R_{G} =1 Ω , I_{D} =1A ,RL=15 Ω .		11	21	
Tr	Rise Time			13	24	
T _{d(off)}	Turn-Off Delay Time			37	67	ns
T _f	Fall Time			11	21	
C _{iss}	Input Capacitance	V _{DS} =20V , V _{GS} =0V , f=1MHz		1460		
C _{oss}	Output Capacitance			180		pF
C _{rss}	Reverse Transfer Capacitance			146		

Diode Characteristics

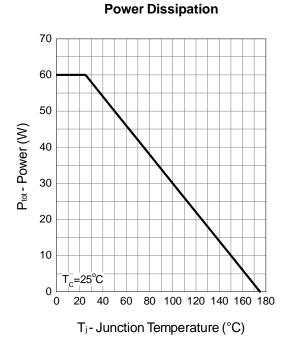
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			40	Α
I _{SM}	Pulsed Source Current ^{2,6}	VG-VD-UV , FOICE Current			100	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =20A , T _J =25℃		0.8	1.3	V

Note

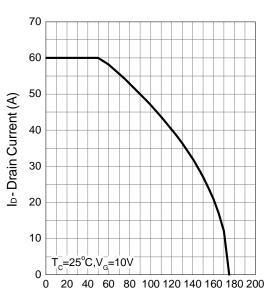
- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec .
- 2.The data tested by pulsed , pulse width $\, \leqq \,$ 300us , duty cycle $\, \leqq \,$ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.5mH, I_{AS} =20A
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.
- 7. Package limitation current is 60A.



Typical Characteristics

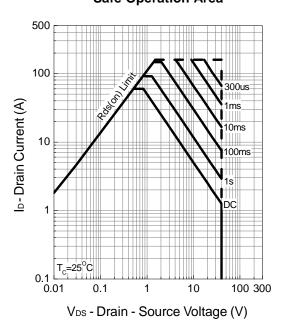


Drain Current

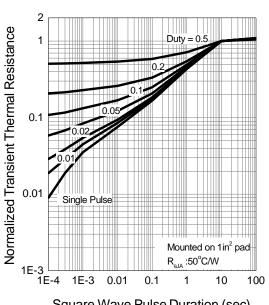


T_j- Junction Temperature (°C)

Safe Operation Area



Thermal Transient Impedance

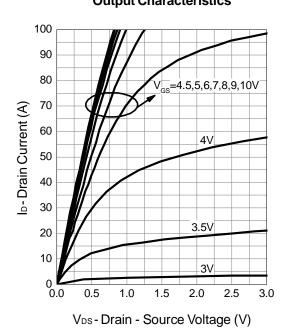


Square Wave Pulse Duration (sec)

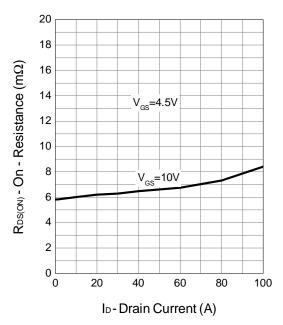


Typical Characteristics

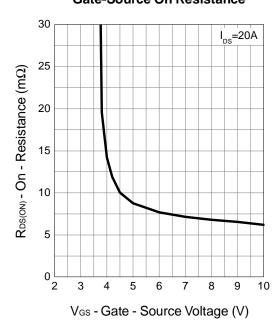
Output Characteristics



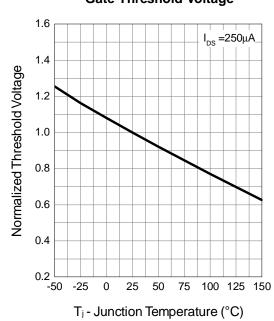
Drain-Source On Resistance



Gate-Source On Resistance



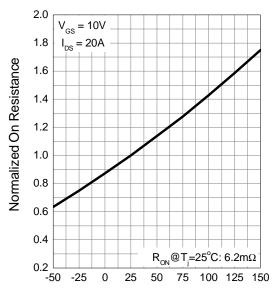
Gate Threshold Voltage





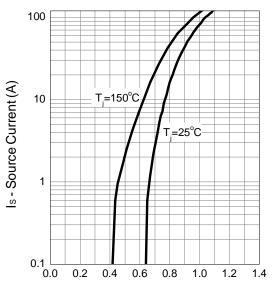
Typical Characteristics

Drain-Source On Resistance



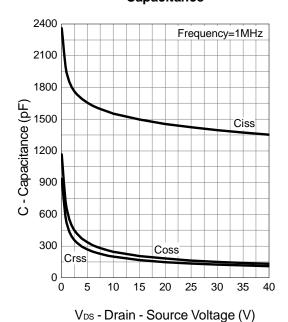
T_j-Junction Temperature (°C)

Source-Drain Diode Forward

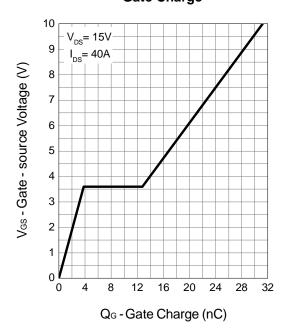


VsD - Source - Drain Voltage (V)

Capacitance



Gate Charge





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